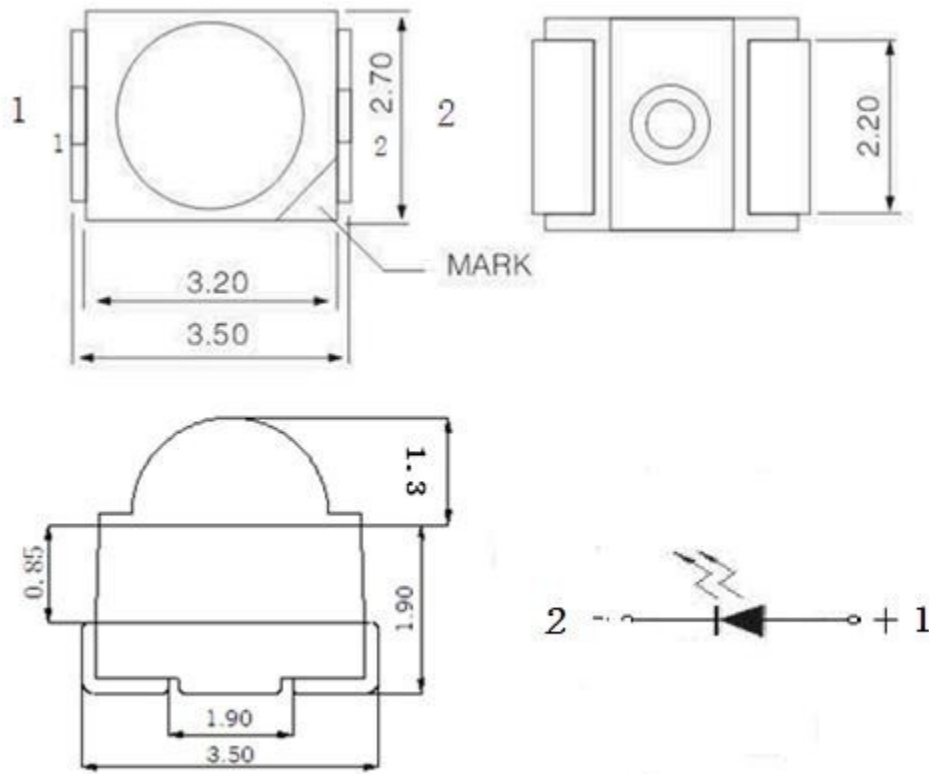

Approve Sheet

/Product	LED
/Part Number	IE-3528PG-SB-L-A01-Y
/Issue Date	
/customer specification	
/Customer	
(Lm/mcd)	IV:2500-3500mcd
/VF (V)	VF: 3.0-3.4v
(Wd)	WL:515-525nm
/CRI	
/other request	
/remarks	

■ Package Dimensions:



“小红帽” 系列



Notes

- Tolerance is $\pm 0.25\text{mm}$ (.010") unless otherwise noted.
- Protruded resin under flange is 1.0mm(.04") max.
- Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.

Absolute Maximum Ratings at TA=25

Parameter	Valce	Unit
Power Dissipation	60	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse width)	50	mA
Continuous Forward Current	20	mA
Derating Linear From 50°C	0.4	mA /°C
Reverse Voltage	5	V
Test temperature	-40°C to +85°C	
Storage Temperature Range	-0°C to +40°C	
Lead Soldering Temperatur Δ [4mm (.157") From Body]	260°C for 5 Seconds	

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min	Typ.	Max	Unit	Test Condition
wave length(λ_d)	Wd	515	--	525	nm	IF=20mA
Forward Voltage (R)	VF	3.0	3.2	3.4	V	
Viewing Angle	2θ1/2	50	--	60	deg	
Reverse Current	IR	--	--	5	μA	VR=5V

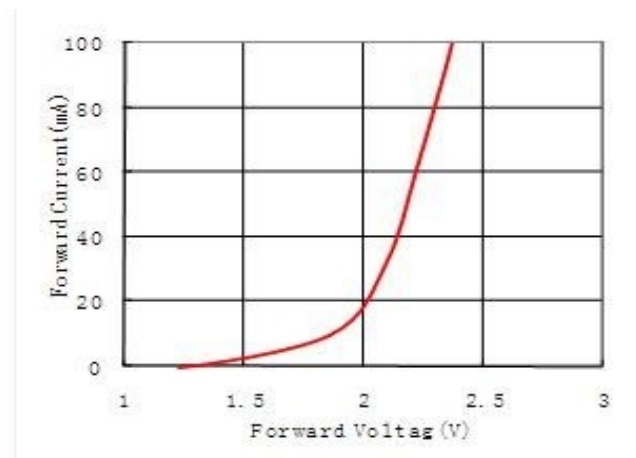
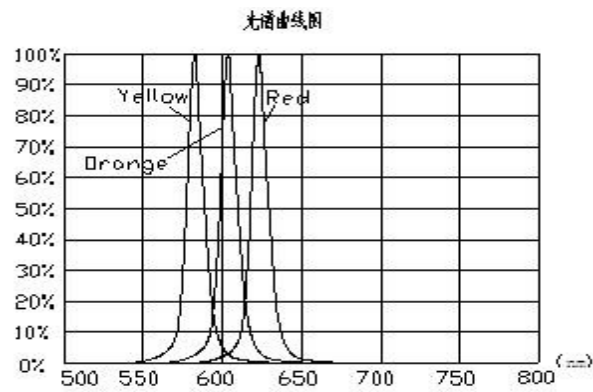
Notes. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission International De L'Eclairage) eye-response curve. 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous and intensity. The dominant wavelength, λ_d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device. The IV guarantee should be added $\pm 15\%$.

INTENSITY BIN LIMIT (IF=20mA)

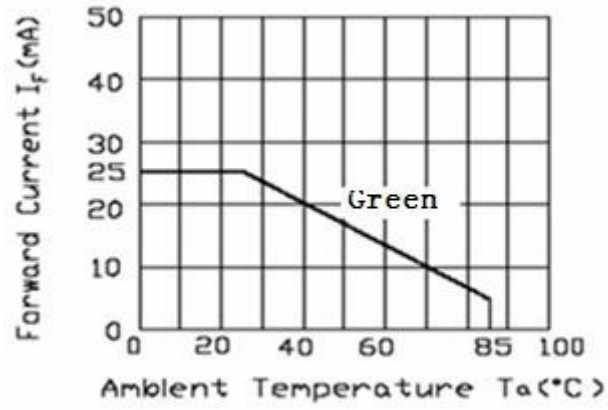
Bin Code	Min(nm)	Max(nm)
A	515	520
B	520	525

Bin Code	Min(V)	Max(V)
A	3.0	3.2
B	3.2	3.4

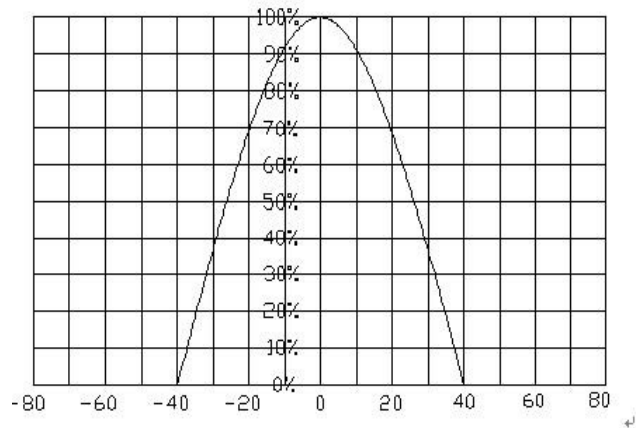
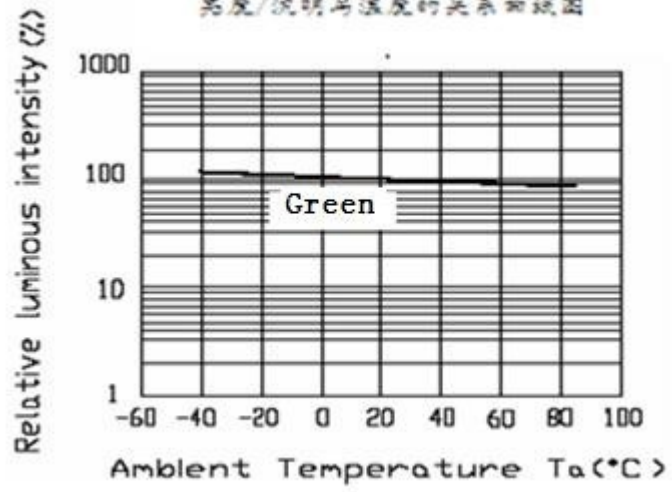
Optical Characteristics



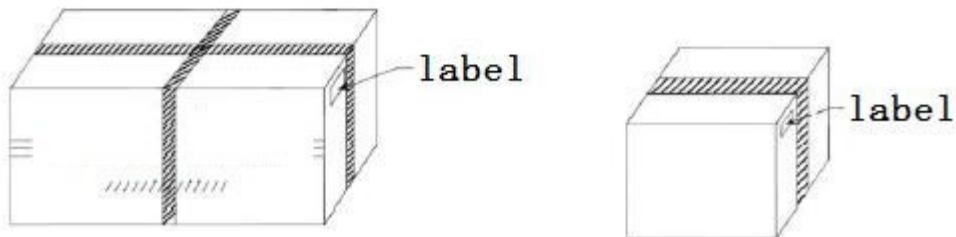
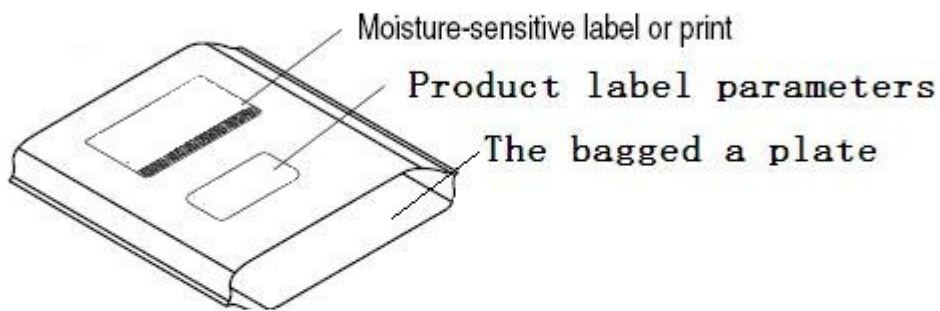
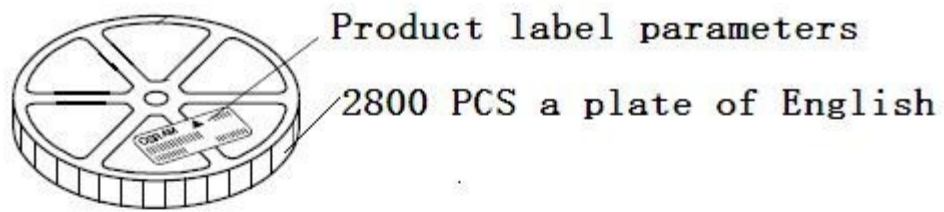
电流与温度关系的曲线图



亮度/流明与温度的关系曲线图



Led packaging in English



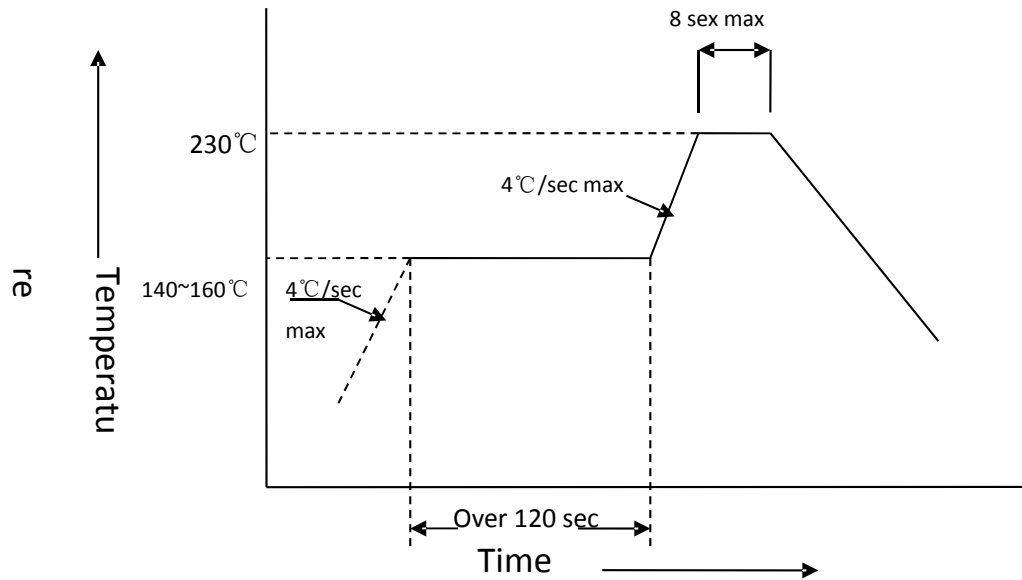
A case of 14 k in English

Reflow Soldering Instructions

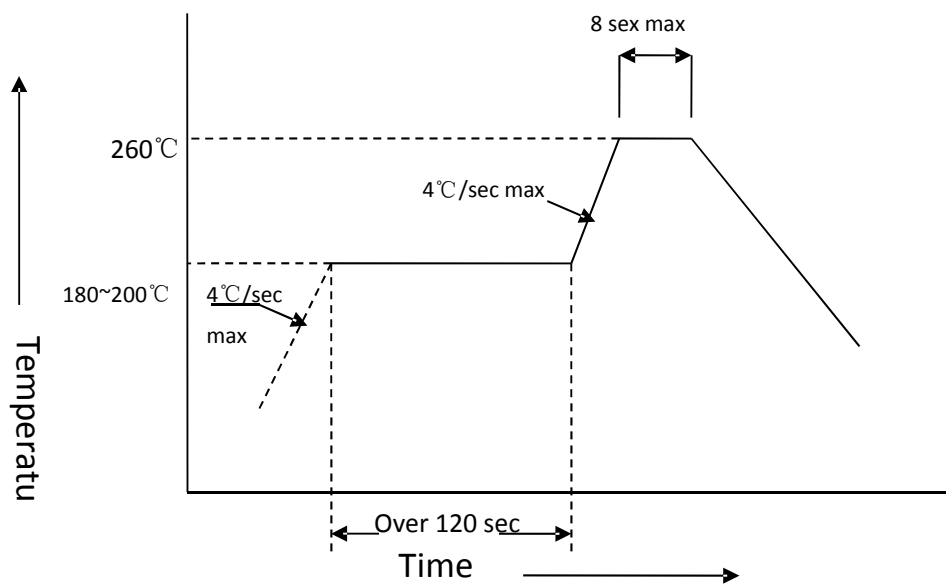
Number of reflow process shall be less than 2 times and cooling

process to normal temperature is required between first and Second soldering process.

1>Lead Solder

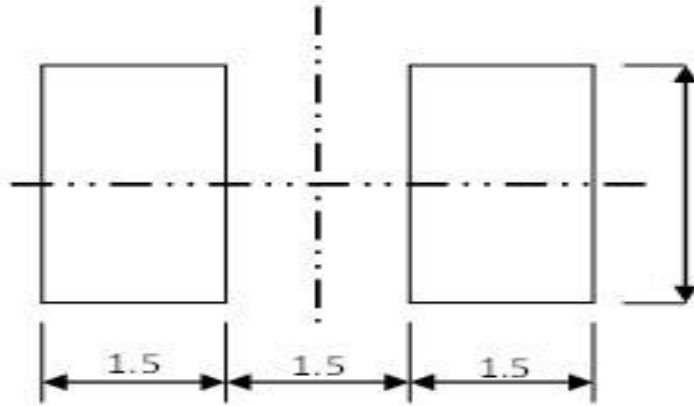


2>Lead-Free Solder



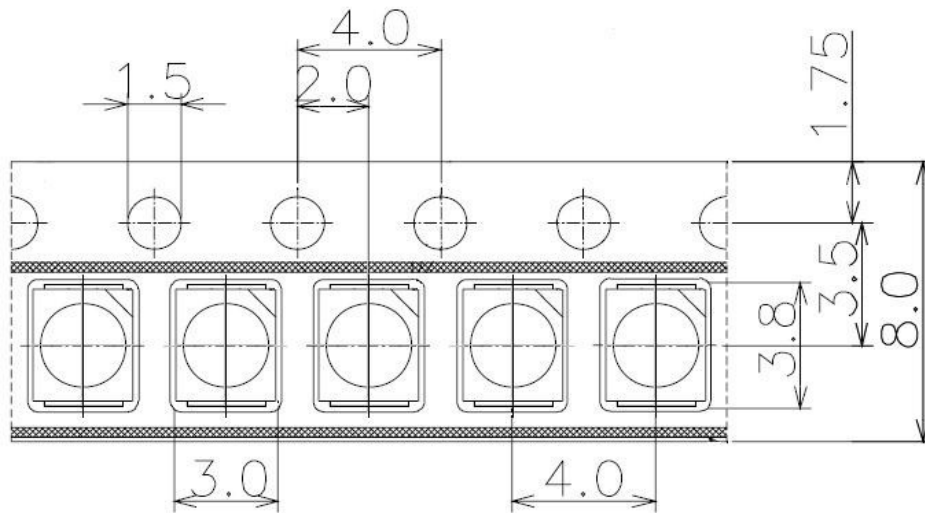
Recommended Soldering Pattern

<Units:mm>



Method of Taping / Polarity and Orientation

Packing unit 2000/reel, $\varnothing 180$ mm



Adhesion Strength of Cover Tape : Adhesion strength to be 0.1– 0.7N when the cover tape is turned off from the carrier at 10° angle to be the carrier tape.

SMD LED

